

ABSTRACT OF THE DISCLOSURE

Field repairable system-on-a-chip (SOC) devices are possible by including electrically programmable circuits on the device, for example in the embedded memory of the SOC device. The SOC device may undergo a conventional repair process prior to packaging the device for field operation. In addition to the conventional repair process, usage indicator may be marked prior to packaging. In the field, if the embedded memory of the SOC device fails to operate correctly, diagnostic programs may be run to identify the faulty rows and/or columns. Redundant rows and/or columns may be electrically programmed in the field to repair the SOC device. Multiple field repairs can be accomplished by using this invention.

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